

Sensors and Materials

Special Issue on Remote Sensing and Sensing Devices

Call for Papers

In the age of the Internet of Things (IoT), information from sensors will be collected using wireless network systems. Therefore, it is necessary to extend the lifetime of wireless sensors. The aim of this special issue will focus on all aspects of research and development related to sensor materials, sensor circuits, low-power sensor devices, MEMS, packaging, wireless circuits for sensors, remote sensing, sensor network, and energy harvesting circuits for sensor batteries.

Scope:

- Sensor materials
- Low-power sensor devices
- Packaging
- Remote sensing
- Energy harvesting circuits
- Sensor circuits
- MEMS
- Wireless circuits for sensors
- Sensor network
- Related sensor systems

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